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	PATENT NUMBER
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U.S. <b>UTILITY</b> Patent Application	

PATENT DATE O.I.P.E. SCANNED

APPLICATION NO. CONT/PRIOR CLASS SUBCLASS ART UNIT EXAM....R F 09/932943 106 £ (\*.)

Gaku Minamihaba Hiroyuki Yano Nobuyuki Kurashima Nobuo Kawahashi

Slurry for chemical mechanical polishing and method of manufacturing semiconductor device

PTO-2040 12/99

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ISSUING CLASSIFICATION						
ORIGIN	AL	CROSS REFERENCE(S)				
CLASS	SUBCLASS	SS CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)			
INTERNATIONA	L CLASSIFICATION	M				
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TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED		
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.	
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subsequent to (date) has been disclaimed.	(Assistant	Exeminer)	(Date)			
☐ The term of this patent shall						
not extend beyond the expiration date of U.S Patent. No.				ISSUE FEE		
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this patent have been disclaimed.	(Legal Instrume	ents Examiner)	(Date)			
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orm PTO-436A Rev. 6/99)		·	FILED WITH:	DISK (CRF)	FICHE CD-RO	

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